

April 2008

FGA180N33AT 330V, 180A PDP Trench IGBT

Features

- · High Current Capability
- Low saturation voltage: V_{CE(sat)} =1.03V @ I_C = 40A
- High input impedance
- · RoHS compliant

Applications

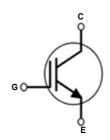
PDP SYSTEM



General Description

Using Novel Trench IGBT Technology, Fairchild's new series of trench IGBTs offer the optimum performance for PDP applications where low conduction and switching losses are essential.





Absolute Maximum Ratings

Symbol	Description		Ratings	Units	
V _{CES}	Collector to Emitter Voltage		330	V	
V_{GES}	Gate to Emitter Voltage		± 30	V	
I _C	Collector Current	@ $T_C = 25^{\circ}C$	180	A	
I _{C pulse (1)}	Pulsed Collector Current	@ T _C = 25°C	450	A	
P _D	Maximum Power Dissipation	@ T _C = 25°C	390	W	
ן י ט	Maximum Power Dissipation	$@ T_C = 100^{\circ}C$	156	W	
TJ	Operating Junction Temperature		-55 to +150	°C	
T _{stg}	Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

Notes

1: Repetitive test, pulse width = 100usec, Duty = 0.1

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units	
$R_{\theta JC}$ (IGBT)	Thermal Resistance, Junction to Case	-	0.32	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W	

^{*} I_C pulse limited by max Tj

Package Marking and Ordering Information

			Packaging		Max Qty per	
Device Marking	Device	Package	Туре	Qty per Tube	Box	
FGA180N33AT	FGA180N33ATTU	TO-3P	Tube	30ea	-	

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250\mu A$	330	-	-	V
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	250	μΑ
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 250uA$, $V_{CE} = V_{GE}$	2.5	4.0	5.5	V
, ,		I _C = 40A, V _{GE} = 15V	-	1.1	1.4	V
V05()	Collector to Emitter Saturation Voltage	I _C = 180A, V _{GE} = 15V,	-	1.68	-	V
V _{CE(sat)} Collector to Emitter Saturation Voltage	$I_C = 180A, V_{GE} = 15V$ $T_C = 125^{\circ}C$	-	1.89	_	V	
Dynamic C	haracteristics			ı	ı	
C _{ies}	Input Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$ f = 1MHz	-	3880	-	pF
C _{oes}	Output Capacitance		-	305	-	pF
C _{res}	Reverse Transfer Capacitance	- 1 = 11VII 12	-	180	-	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time		-	27	-	ns
t _r	Rise Time	V_{CC} = 200V, I_{C} = 40A, R_{G} = 5 Ω , V_{GE} = 15V, Resistive Load, T_{C} = 25°C	-	80	-	ns
t _{d(off)}	Turn-Off Delay Time		-	108	-	ns
t _f	Fall Time		-	180	240	ns
t _{d(on)}	Turn-On Delay Time		-	26	-	ns
t _r	Rise Time	V_{CC} = 200V, I_{C} = 40A, R_{G} = 5 Ω , V_{GE} = 15V, Resistive Load, T_{C} = 125°C	-	75	-	ns
t _{d(off)}	Turn-Off Delay Time		-	112	-	ns
t _f	Fall Time		-	250	300	ns
Q _g	Total Gate Charge		-	169	-	nC
Q _{ge}	Gate to Emitter Charge	$V_{CE} = 200V, I_{C} = 40A,$	-	22	-	nC
Q _{gc}	Gate to Collector Charge	V _{GE} = 15V	-	69	-	nC

Figure 1. Typical Output Characteristics

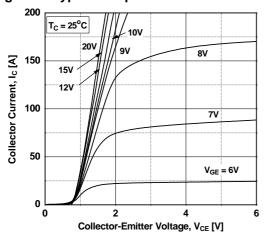


Figure 3. Typical Saturation Voltage Characteristics

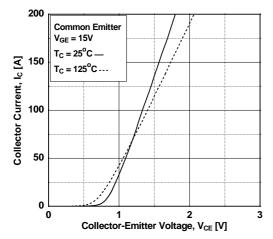


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

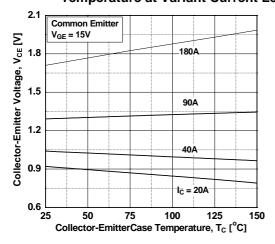


Figure 2. Typical Output Characteristics

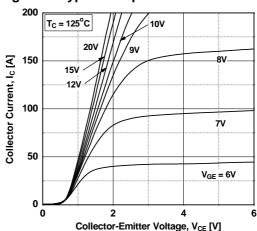


Figure 4. Transfer Characteristics

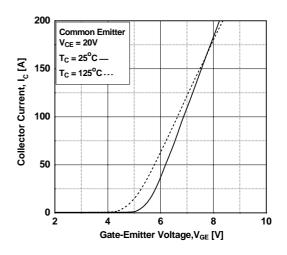


Figure 6. Saturation Voltage vs. V_{GE}

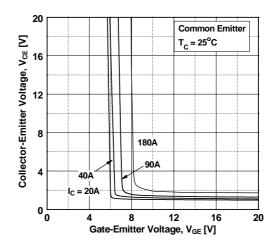


Figure 7. Saturation Voltage vs. V_{GE}

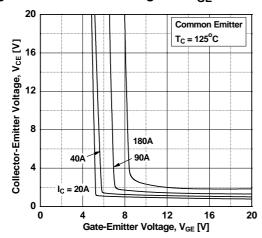


Figure 9. Gate charge Characteristics

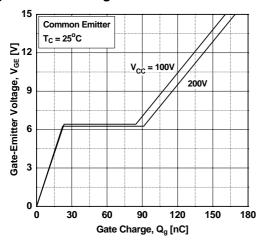


Figure 11. Turn-on Characteristics vs.
Gate Resistance

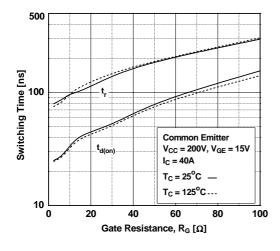


Figure 8. Capacitance Characteristics

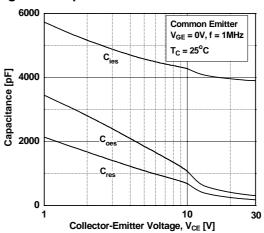


Figure 10. SOA Characteristics

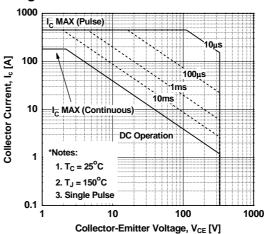


Figure 12. Turn-off Characteristics vs.
Gate Resistance

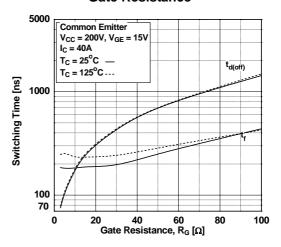


Figure 13. Turn-on Characteristics vs. Collector Current

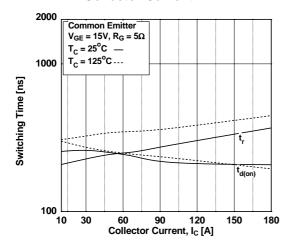


Figure 14. Turn-off Characteristics vs. Collector Current

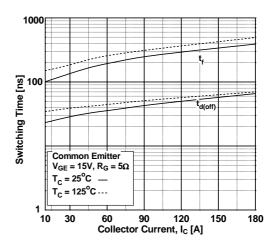
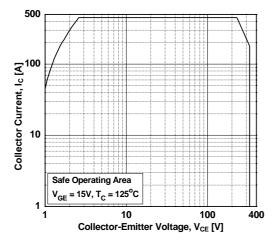
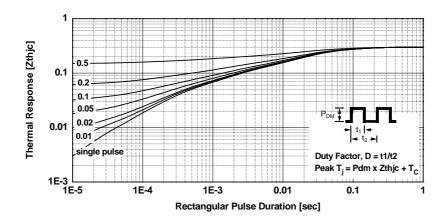


Figure 15. Turn off Switching SOA Characteristics

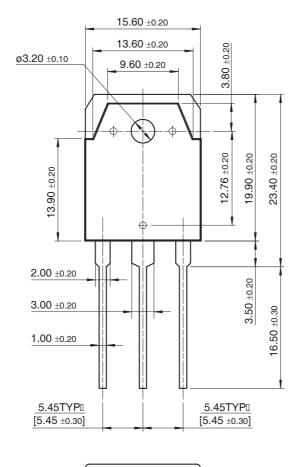


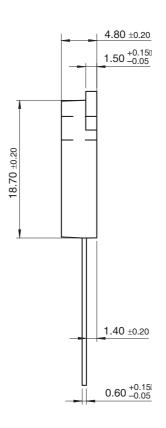




Mechanical Dimensions

TO-3P





Dimensions in Millimeters





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